IEEE P802.3ck Ad Hoc meeting – April 24, 2019

Prepared by Kent Lusted

Proposed Agenda:

- Approval of the Agenda
- Approve 10 April 2019 ad hoc minutes
- IEEE Patent Policy reminder:
 - http://www.ieee802.org/3/patent.html
- IEEE Participation Requirements reminder
- Logistics for May Interim meeting
- Status of the Task Force
- .3ck Ad Hoc
 - "Working toward ERL limit baseline for C2M", Rich Mellitz
 - "CR/KR Considerations for c(-3) tap", Margaret Johnson
 - "Details of 4-lane Interleaved 100G FEC", Shawn Nicholl & Ben Jones

Presentations posted at: http://www.ieee802.org/3/ck/public/adhoc/index.html

Meeting began at ~7:05 a.m. Pacific by Beth Kochuparambil.

Meeting began with the agenda presentation:

http://www.ieee802.org/3/ck/public/adhoc/apr10 19/agenda 042419 3ck adhoc.pdf

The ad hoc chair reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes. Reminded participants to mute lines when not speaking and reviewed the steps to unmute.

Showed the links to the IEEE P802.3ck Task Force ad hoc page and the email reflector.

Presented the proposed agenda. There was no opposition. The agenda was approved by the ad hoc.

Chair noted that the April 10, 2019 minutes were posted. She asked if there were corrections or modifications. No one responded. Minutes were approved by the Task Force.

Reminded participants of the IEEE patent policy. She asked if anyone was unfamiliar with the IEEE patent policy. No one responded.

Reminded participants of the IEEE Participation Requirements and showed the slide with the Participation requirements. She asked if anyone was unfamiliar with the IEEE Participation Requirements. No one responded.

Agenda Items

P802.3ck Update, Beth Kochuparambil

See:

- Next meeting is the week of May 20, 2019 in Salt Lake City, Utah, USA. The Task Force will meet Tuesday-Thursday.
- Request for presentations due Friday, May 10, 2019 AoE. Presentations due 5pm Pacific, Wednesday, May 15, 2019.
- Goal: adopt baselines and work towards draft 1.0
- It was noted that the outline of topics is very rough and subject to change.

Presentation #1:

"Working toward ERL limit baseline for C2M", Rich Mellitz

See: http://www.ieee802.org/3/ck/public/adhoc/apr24 19/mellitz 3ck adhoc 01a 042419.pdf

- Analysis uses COM version 2.66, which has the same functionality as v2.60 posted to the website for these calculations.
- Discussed the use of VEO vs. VEC. There was concern that the VEC calculation method was not ideal.
- On slide 5, the graph on the right is a histogram of VEO.
- There was a request to run ERL looking into the module.

There was a technical difficulty with the audio for a presenter. Chair asked if there was objection to swapping the order of Margaret Johnson presentation with Shawn Nicholl's presentation. No one objected.

Presentation #2:

"Details of 4-lane Interleaved 100G FEC", Shawn Nicholl & Ben Jones

See: http://www.ieee802.org/3/ck/public/adhoc/apr24 19/nicholl 3ck adhoc 01b 042419.pdf

- Updated version '01b' with editorial and clarifying corrections. No objection.
- Clarification on slide 13. 4:1 (green curve) is similar to 400G performance; re-use of circuitry would still keep the performance at or better than 400G.
- Latency impact of re-use of circuitry (vs the initial interleaved FEC proposal) is expected to be negligible.

Presentation #3:

"CR/KR Considerations for c(-3) tap", Margaret Johnson

See: http://www.ieee802.org/3/ck/public/adhoc/apr24 19/johnston 3ck adhoc 01 042419.pdf

- Discussion on COM use vs implementation
- Discussion of COM impact from inclusion of tap in COM
- Discussion of cost of implementation and link training

Chair noted that the next ad hoc is May 8 followed by presentation requests for face-to-face is due May 10.

The ad hoc meeting ended at ~8:50 a.m. Pacific.

List of attendees (captured from Webex tool)

Name Affiliation Employed by

Adam Healey Broadcom Broadcom

Adrian Butter Global Foundries Global Foundries

Alex Bailes Keysight Keysight

Alex Haser Molex Molex

Ali Ghiasi Quantum Ghiasi Quantum & Huawei

Amanda Dong Xilinx Xilinx

Andy Zambell Amphenol Amphenol

Arturo Pachon Cisco Cisco

Bert Klaps Intel Intel

Beth Kochuparambil Cisco Cisco

Bill Kirkland Semtech Semtech

Bo Zhang Inphi Inphi

Brandon Gore Samtec Samtec

Brian Holden Kandou Kandou

Bruce Champion TE Connectivity TE Connectivity

Burrell Best Samtec Samtec

Chien-Ping Kao Intel Intel

David Malicoat Senko Malicoat Networking Solutions

David Ofelt Juniper Juniper

David Piehler Dell EMC Dell EMC

David Rennie Synopsys Synopsys

Dean Wallace Marvell Marvell

Derek Wang Cenec Networks Cenec Networks

Frank Lambrecht Gigamon Gigamon

Gary Nicholl Cisco Cisco

Geoff Zhang Xilinx Xilinx

Greg McSorley Amphenol Amphenol

Hormoz Djahanshahi Microsemi Microsemi

Howard Heck Intel Intel

Hsinho Wu Intel Intel

Ilya Lyubumirshky Inphi Inphi

Jane Lim Cisco Cisco

Jeff Slavick Broadcom Broadcom

Jeffery Maki Juniper Juniper

Jeremy Stephens Intel Intel

John D'Ambrosia FutureWei (Subsidiary of FutureWei (Subsidiary of

Huawei) Huawei)

John Ewen Globalfoundries Globalfoundries

Kapil Shrikhande Innovium Innovium

Kent Lusted Intel Intel

Kumaran Krishnasamy Broadcom Broadcom

Leesa Noujeim Google Google

Lokesh Kabra Synopsys Synopsys

Marco Mazzini Cisco Cisco

Margaret Cadence Cadence

Mark Gustlin Cisco Cisco

Masashi Shimanouchi Intel Intel

Matt Brown Macom Macom

Matt Schumacher TE TE

Mau-Lin Wu Mediatek Mediatek

Mike Klempa UNH-IOL UNH-IOL

Ming ran Huawei Huawei

Nathan Tracy TE Connectivity TE Connectivity

Pete Anslow Ciena Ciena

Phil Sun Credo Credo

Piers Dawe Mellanox Mellanox

Pirooz Tooyserkani Cisco Cisco

Rich Mellitz Samtec Samtec

Rick Rabinovich Keysight Keysight

Rita Horner Synopsys Synopsys

Rob Stone Broadcom Broadcom

Sam Kocsis Amphenol Amphenol

Scott Sommers Molex Molex

Shawn Nicholl Xilinx Xilinx

Shimon Muller Axalume Axalume

Stephen Didde Keysight Keysight

Steve Baumgartner Global Foundries Global Foundries

Steve Sekel Keysight Keysight

Takeshi Nishimura Yamaichi Electronics, Yamaichi Electronics, USA

USA

Tao Hu Marvell Marvell

Ted Sprague Infinera Infinera

Tom Palkert Molex/Macom Molex/Macom

Tony Zortea Mellanox Mellanox

Upen Kareti Cisco Cisco

Vittal Balasubramanian Innovium Innovium

Xiang He Huawei Huawei

Xinyuan Wang Huawei Huawei

Yan Zhuang Huawei Huawei

Yasuo Hidaka Credo Credo

Yuchun(Louis) Lu Huawei Huawei